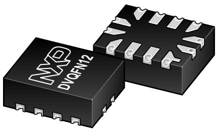
SOT2225-1(DD)

DVQFN12, plastic, dual in-line very thin quad flat package; no leads; 12 terminals; 0.5 mm pitch; 1.95 mm x 2.4 mm x 0.85 mm body

28 April 2025

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	DVQFN12
Package style descriptive code	DVQFN (dual in-line very thin quad flat package; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-04-2025
Manufacturer package code	98ASA02114D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.85	1.95	2.05	mm
package width	2.3	2.4	2.5	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	12	-	

2 Package outline

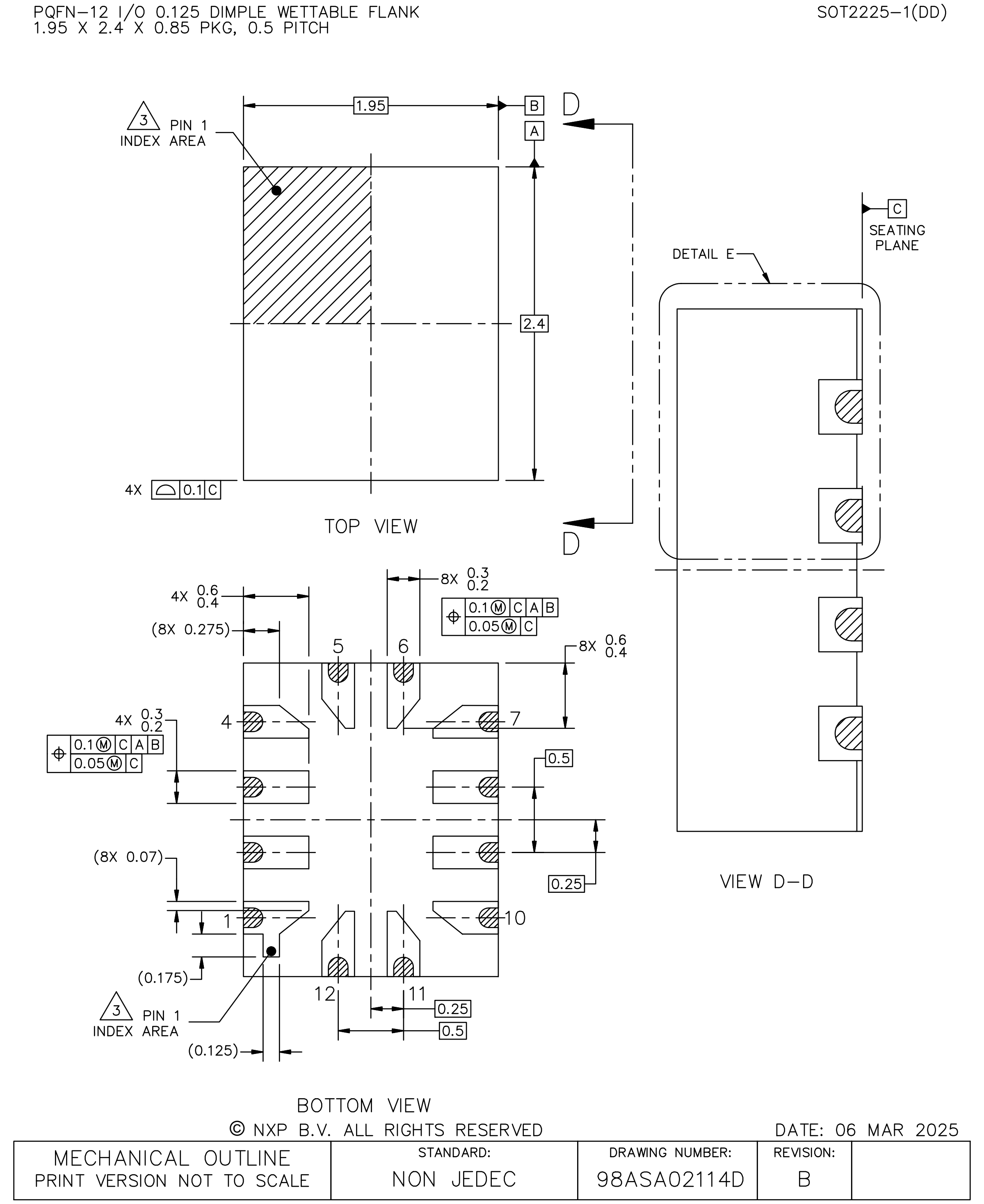
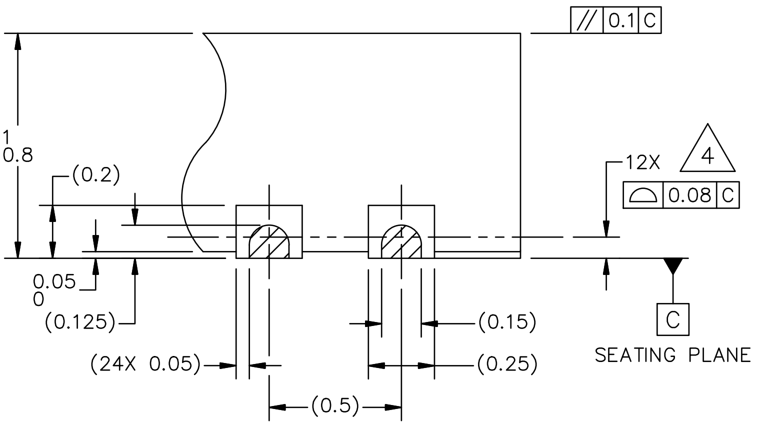


Figure 1. Package outline DVQFN12 (SOT2225-1(DD))

PQFN–12 I/O 0.125 DIMPLE WETTABLE FLANK
1.95 X 2.4 X 0.85 PKG, 0.5 PITCH

SOT2225–1(DD)



DETAIL E
VIEW ROTATED 90° CW

DATE: 06 MAR 2025

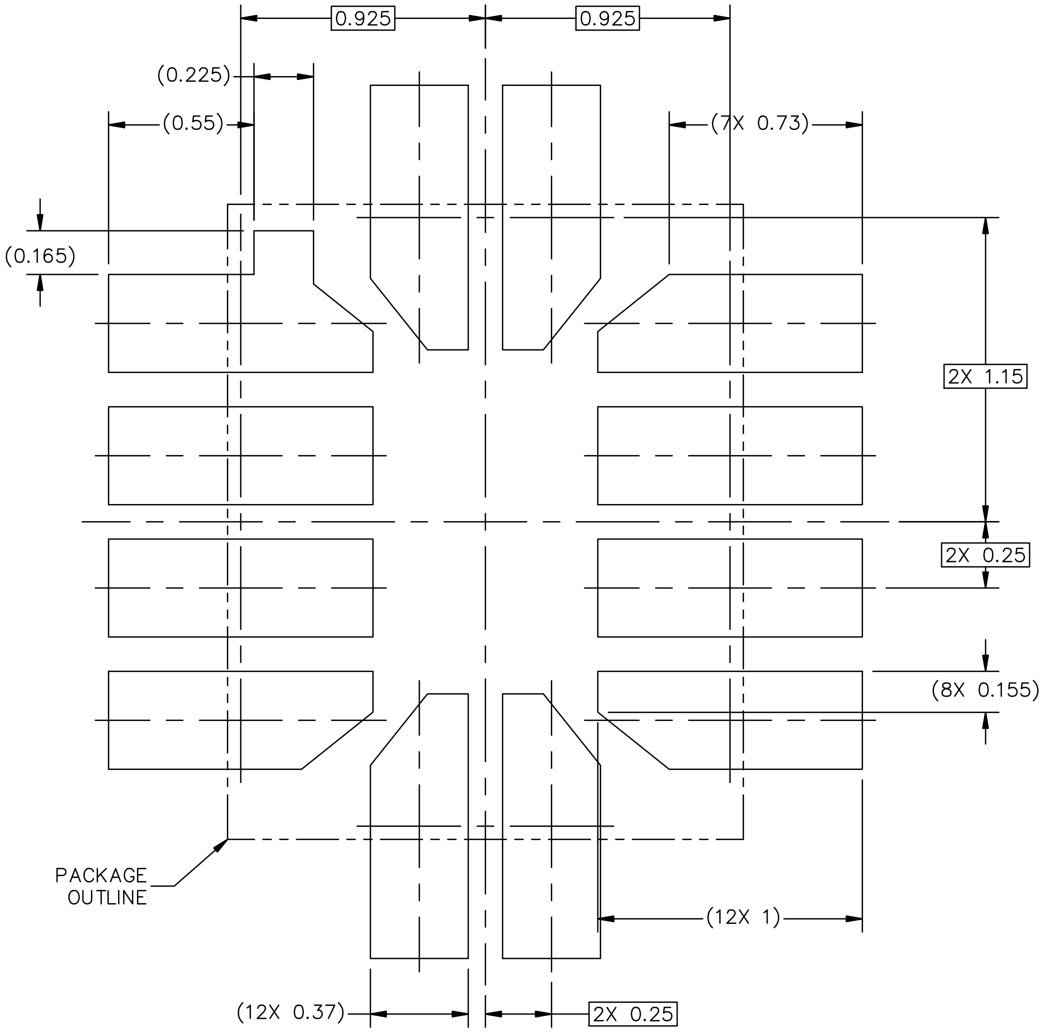
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02114D	REVISION: B	

Figure 2. Package outline detail E of DVQFN12 (SOT2225-1(DD))

3 Soldering

PQFN–12 I/O 0.125 DIMPLE WETTABLE FLANK
1.95 X 2.4 X 0.85 PKG, 0.5 PITCH

SOT2225–1(DD)



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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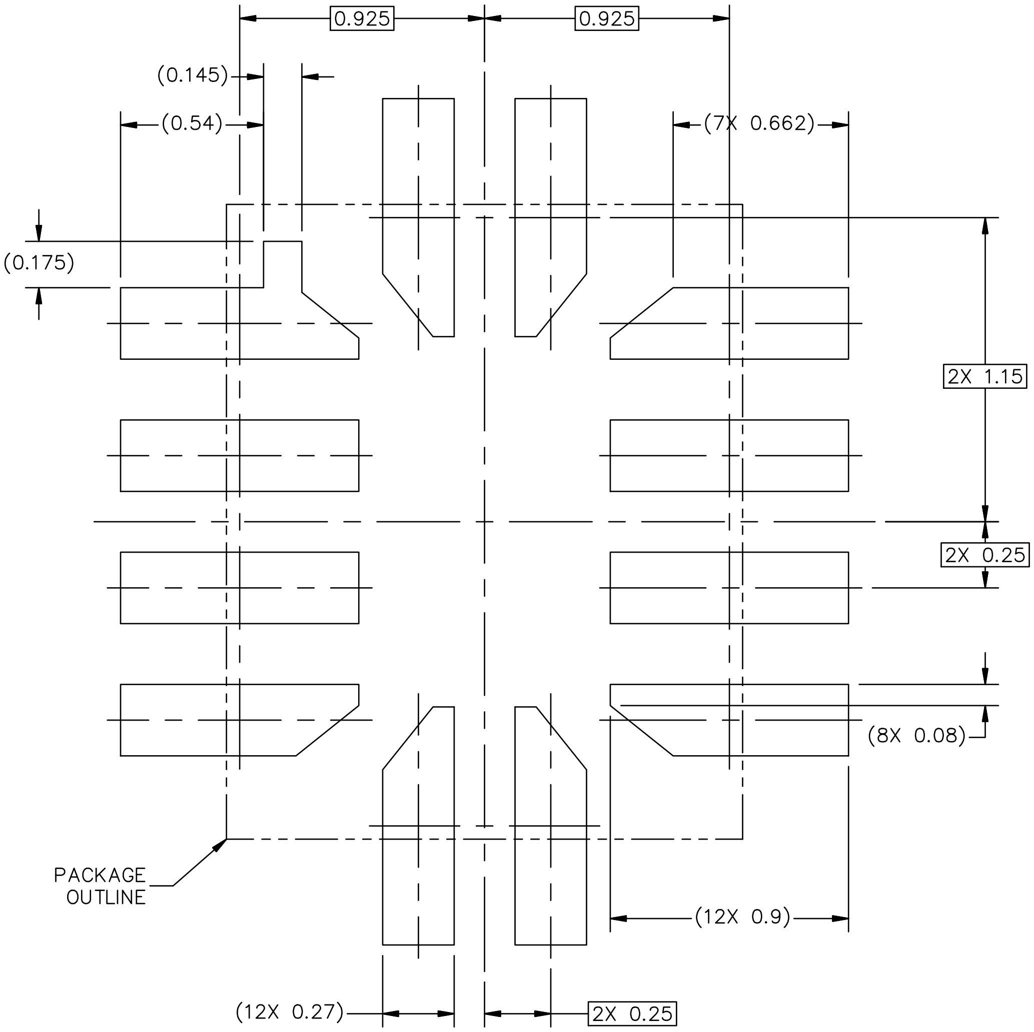
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02114D	REVISION: B	

Figure 3. Reflow soldering footprint part 1 for DVQFN12 (SOT2225-1(DD))

PQFN-12 I/O 0.125 DIMPLE WETTABLE FLANK
1.95 X 2.4 X 0.85 PKG, 0.5 PITCH

SOT2225-1(DD)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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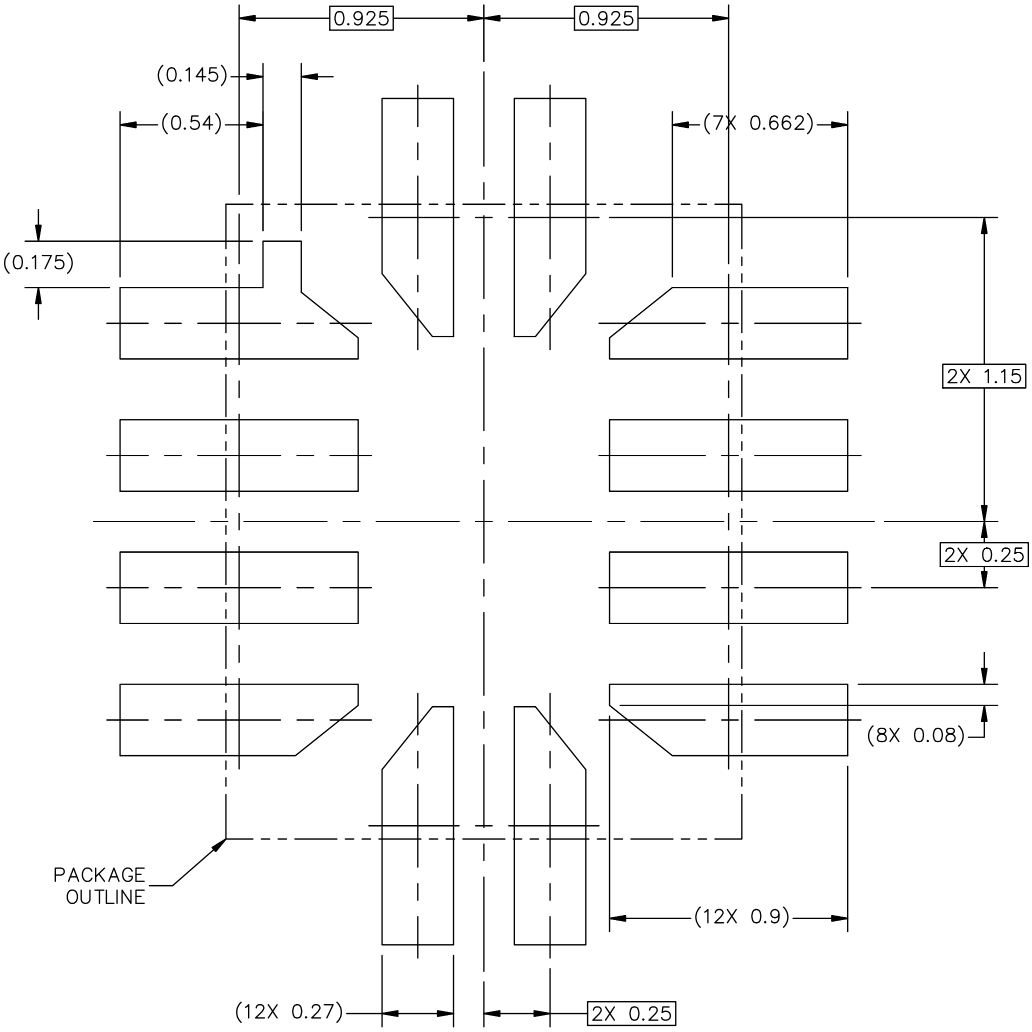
DATE: 06 MAR 2025

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02114D	REVISION: B	

Figure 4. Reflow soldering footprint part 2 for DVQFN12 (SOT2225-1(DD))

PQFN-12 I/O 0.125 DIMPLE WETTABLE FLANK
1.95 X 2.4 X 0.85 PKG, 0.5 PITCH

SOT2225-1(DD)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 06 MAR 2025

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02114D	REVISION: B	

Figure 5. Reflow soldering footprint part 3 for DVQFN12 (SOT2225-1(DD))

PQFN-12 I/O 0.125 DIMPLE WETTABLE FLANK
1.95 X 2.4 X 0.85 PKG, 0.5 PITCH

SOT2225-1(DD)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

DATE: 06 MAR 2025

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02114D	REVISION: B	

Figure 6. Package outline note DVQFN12 (SOT2225-1(DD))

4 Legal information

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